

Title (en)

METHOD FOR THE PRODUCTION OF A MICROELECTRONIC CHIP TO BE HYBRIDISED TO A SECOND CHIP

Title (de)

VERFAHREN ZUR HERSTELLUNG EINES MIKROELEKTRONISCHEN CHIPS ZUR HYBRIDISIERUNG MIT EINEM ZWEITEN CHIP

Title (fr)

PROCEDE DE REALISATION D'UNE PUCE MICROELECTRONIQUE DESTINEE A ETRE HYBRIDEE A UNE DEUXIEME PUCE

Publication

**EP 3529828 A1 20190828 (FR)**

Application

**EP 17792128 A 20171016**

Priority

- FR 1660118 A 20161019
- FR 2017052828 W 20171016

Abstract (en)

[origin: WO2018073517A1] The invention relates to a method for the production of a first microelectronic chip (P1) comprising a layer of interest (13) having a connection surface (11) to be hybridised to a second microelectronic chip (P2), said method comprising the following steps: - deposition of a layer of adhesive (14) on a surface (13a) of the layer of interest (13), opposite the first connection surface (11); attachment of a so-called grip layer (15) to the layer of adhesive (14); and, prior to the steps in which the adhesive is deposited and the grip layer (15) is attached, determination of a maximum thickness (F1) and minimum (F2) and maximum (F3) Young's modulus values for the layer of adhesive (14), and the minimum thickness (F4) for the grip layer (15).

IPC 8 full level

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Citation (search report)

See references of WO 2018073517A1

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